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FOR IMMEDIATE RELEASE

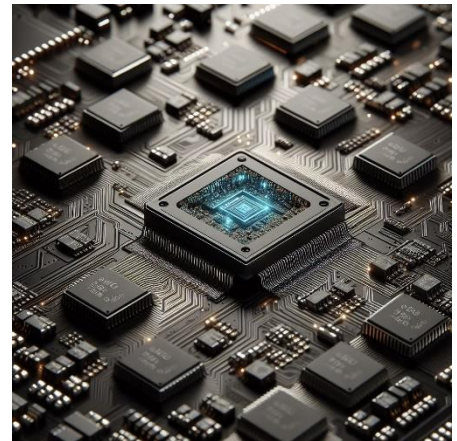
## SHENMAO Debuts Special Solder Paste for AI Substrate Power Management Modules

**SAN JOSE, CA — April 2024** — SHENMAO Technology proudly presents its latest innovation, the PF719-P250A solder paste, specifically designed for AI substrate power management modules. This cutting-edge solder paste represents a significant advancement in thermal fatigue reliability and performance.

SHENMAO has successfully developed the PF719-P250A solder paste with a focus on delivering high anti-thermal fatigue reliability. This innovative product adopts a newly designed lead-free alloy (Sn/3.9Ag/0.6Cu/3.0Sb) that demonstrates exceptional anti-thermal fatigue performance, meeting the stringent demands of modern electronics manufacturing.

### Features of PF719-P250A:

- Halogen-free (ROLO) with no intentionally added halogen, ensuring compliance with RoHS, RoHS 2.0, and REACH standards.
- Outstanding voiding performance, enhancing overall solder joint reliability.
- Superior anti-thermal fatigue performance, ensuring long-term durability in high temperature environments.
- Resistant to multiple reflows, providing consistent performance across various assembly processes.
- Excellent solderability and printability, facilitating smooth and precise application in manufacturing processes.



PF719-P250A has received certification from major power management module manufacturers and has been integrated into the mainstream AI substrate supply chain. Its reliability and performance make it an ideal choice for power management modules in AI applications.

For more information, please visit [www.shenmao.com](http://www.shenmao.com).

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### About SHENMAO

SHENMAO is dedicated to the production of solder products including Water Soluble and No-clean Solder Paste, Laser Solder Paste, Solder Preforms, Cored Solder Wire, Wave Solder Bar Alloys, Wave Soldering Fluxes, Extremely Pure Solder Powder up to Type 8, BGA and Micro BGA Solder Sphere, Wafer Level Packaging Solder Paste and Fluxes, LED Die Attach Paste, High Performance Liquid Fluxes, Solder Preform, Solar Ribbon, Plating Anode used in PCB Fabrication, Assembly and Semiconductor Packaging Processes.